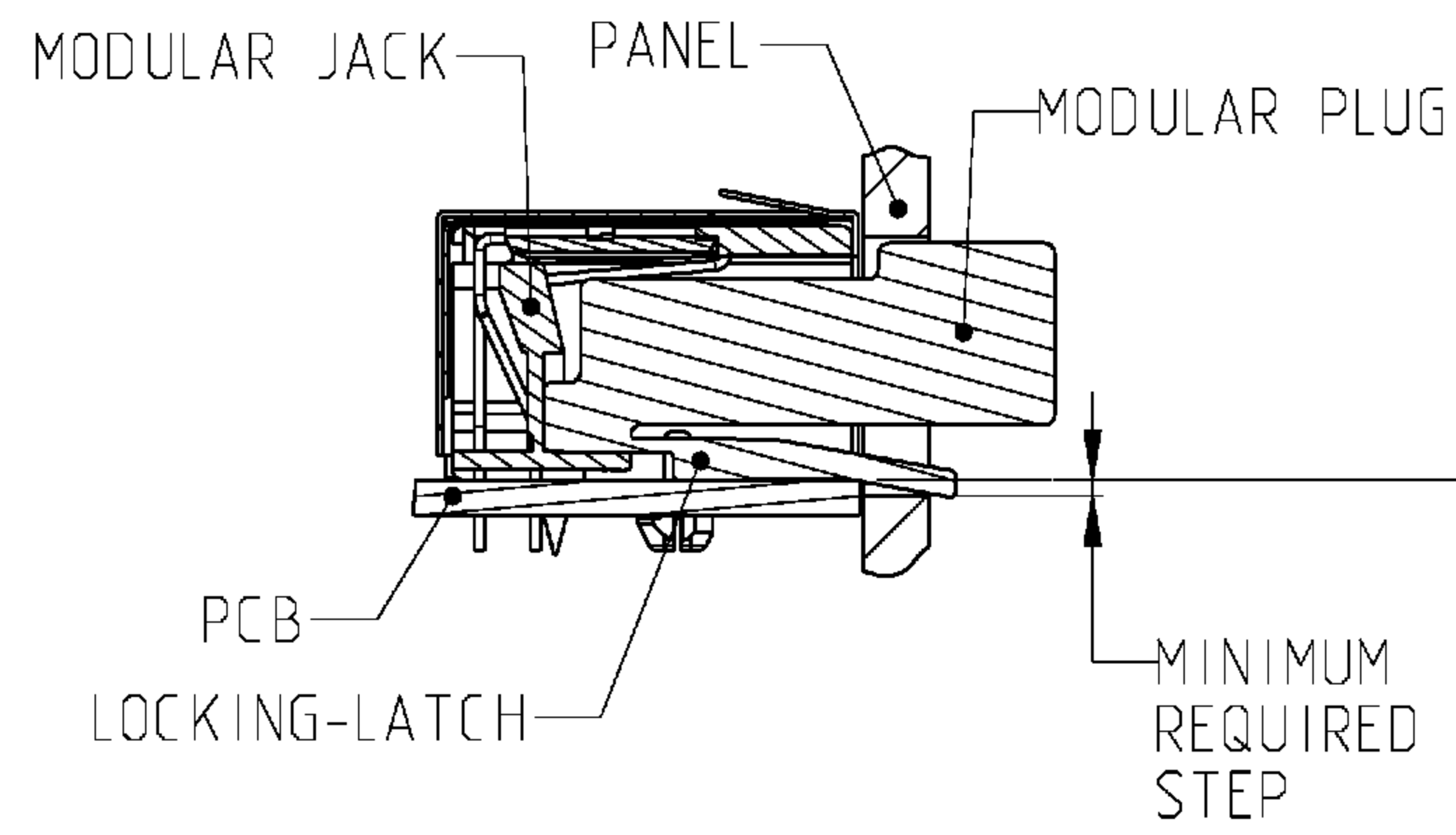


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LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD		
M		ECR-10-02018	21JUN11	PS	RRP		
N		ECR-11-016284	08MAR12	PS	RRP		

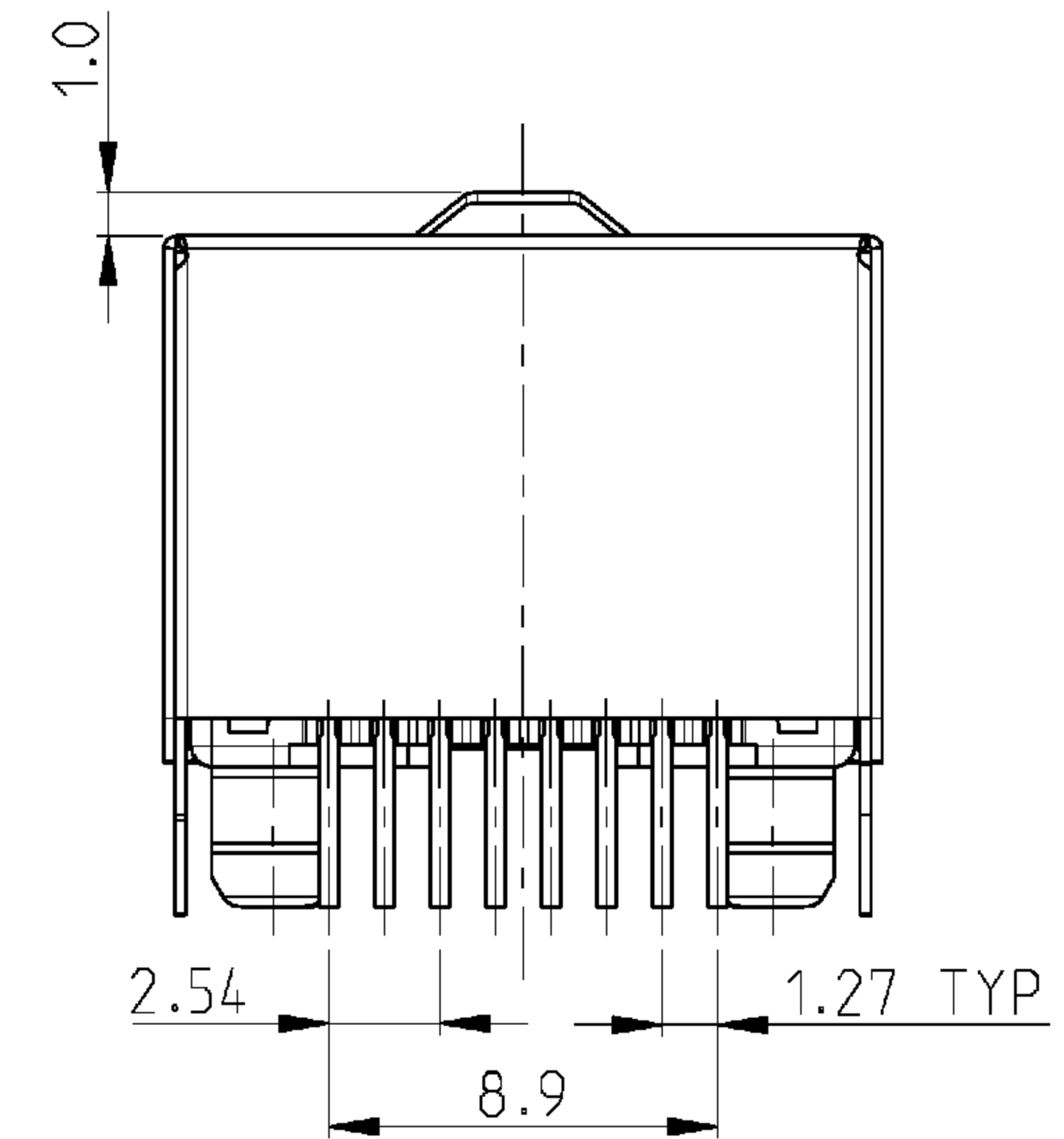
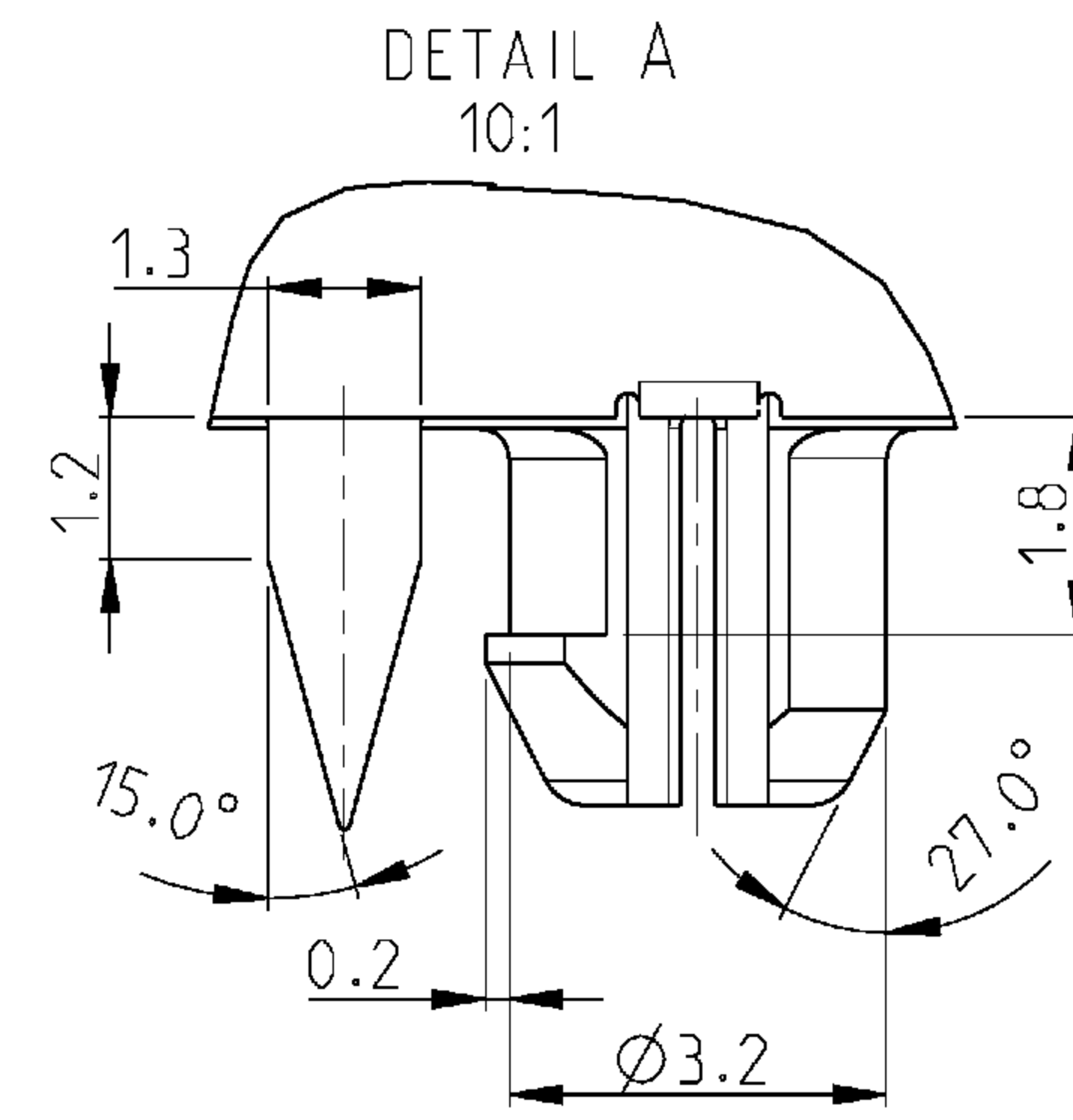
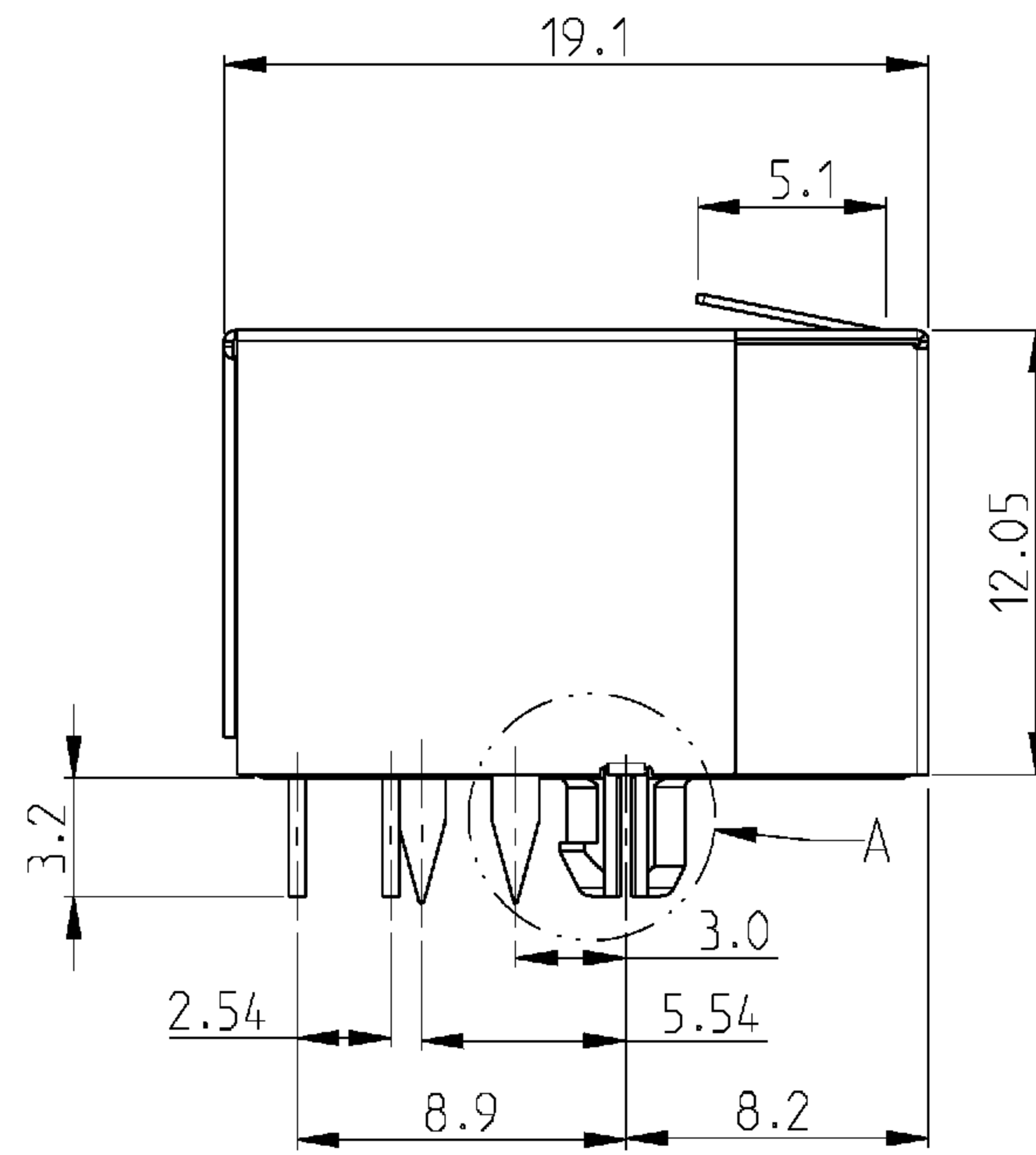
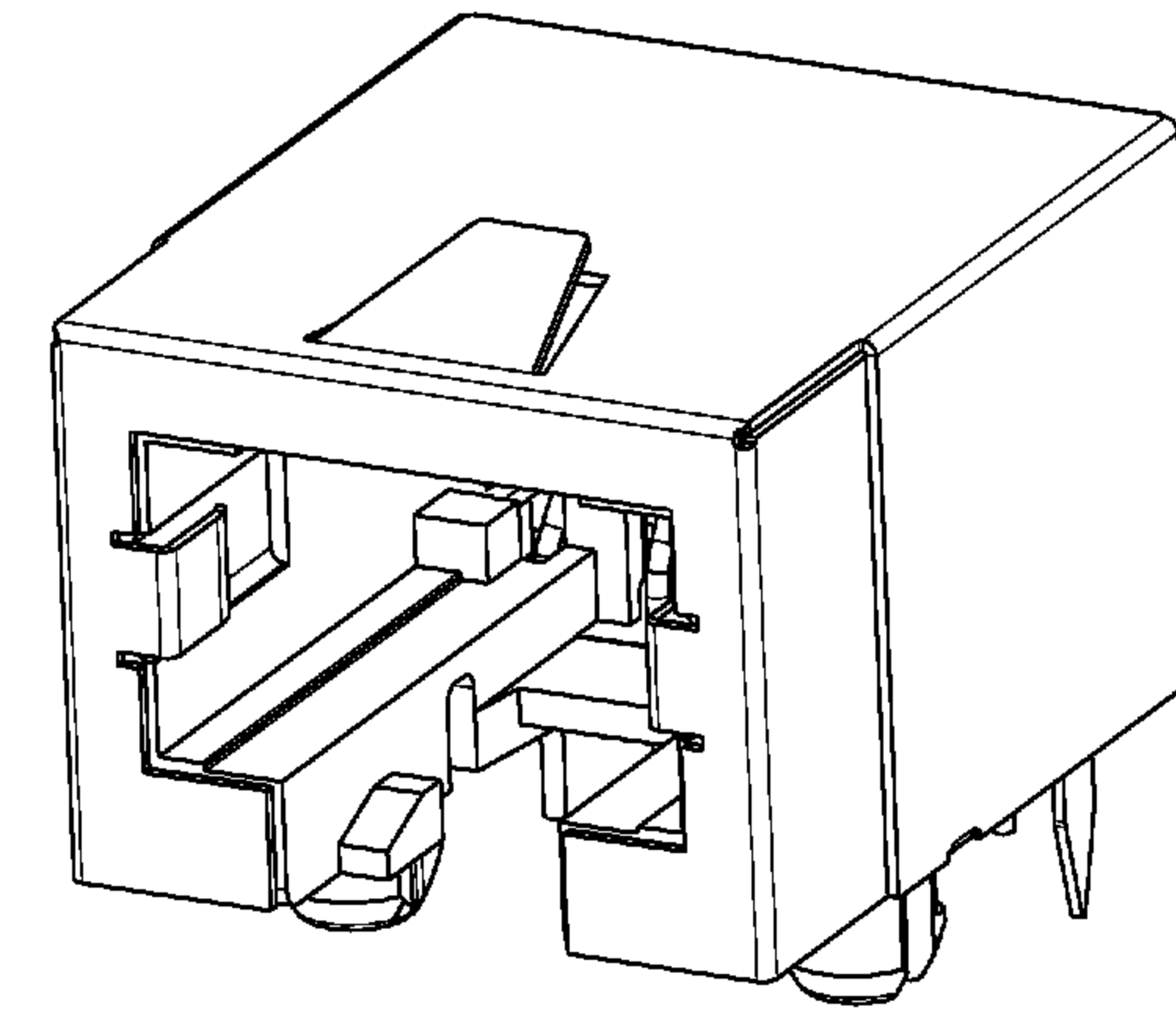
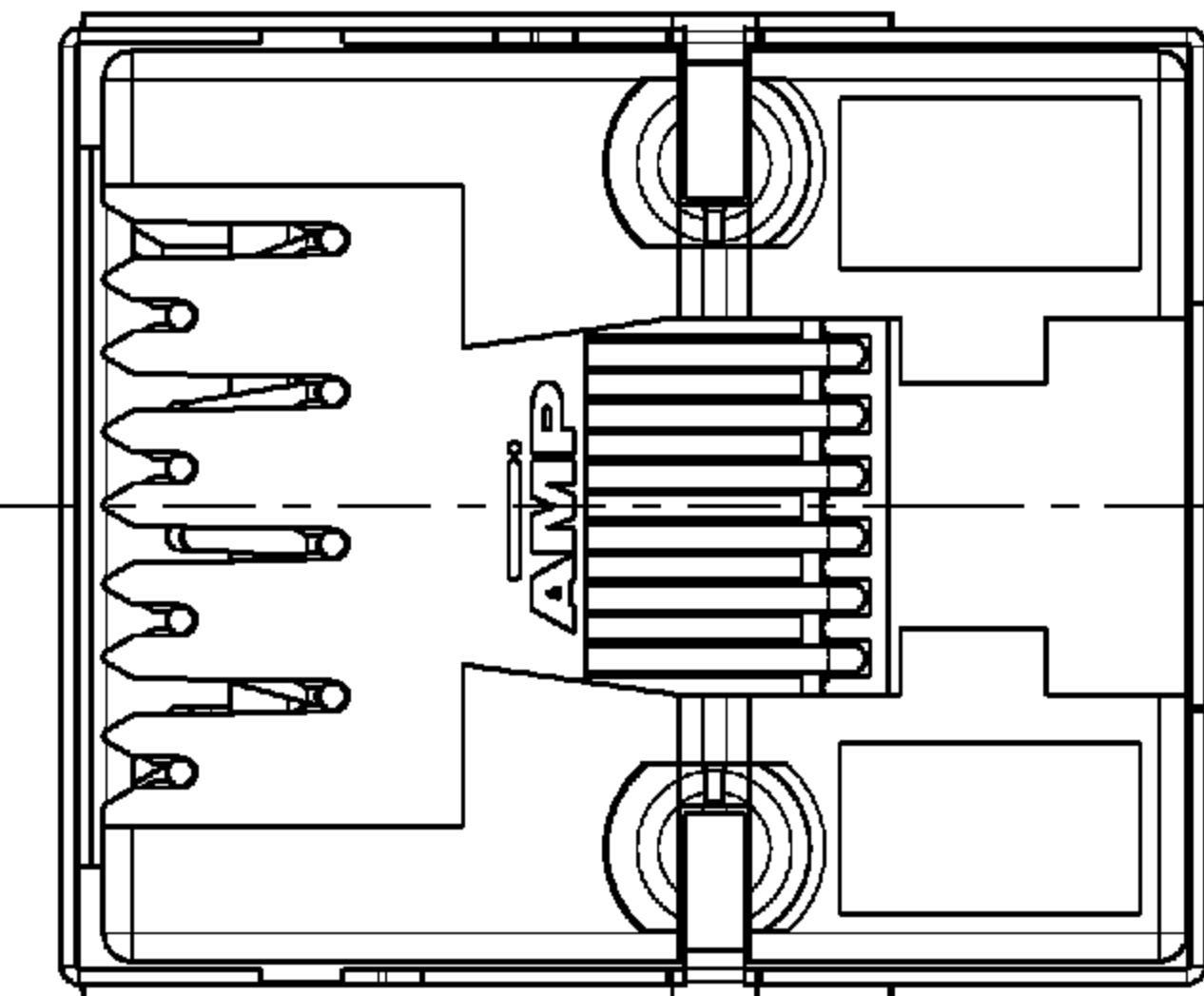
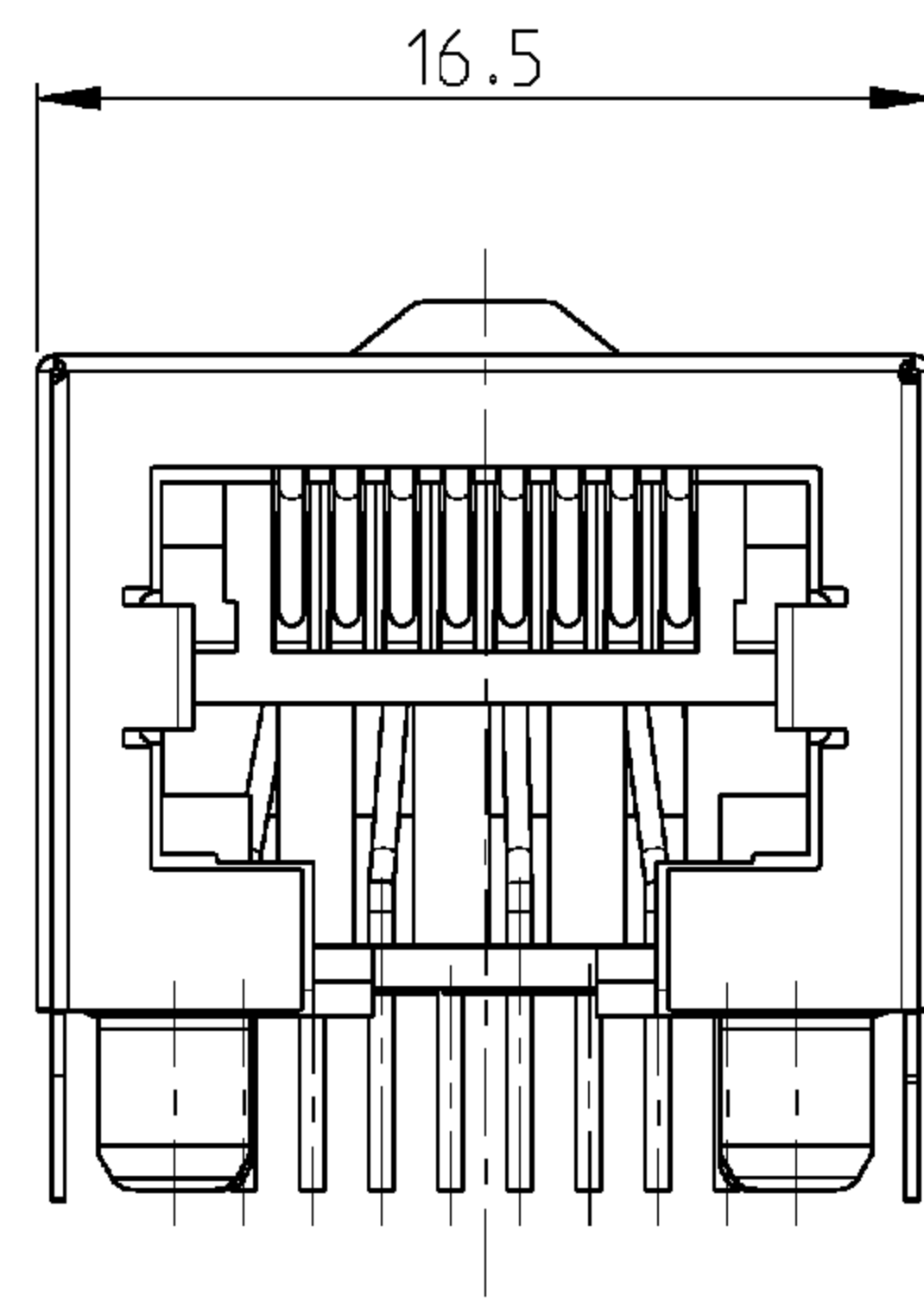
PANEL CUT-OUT DIMENSIONS FOR REAR PANEL MOUNT.



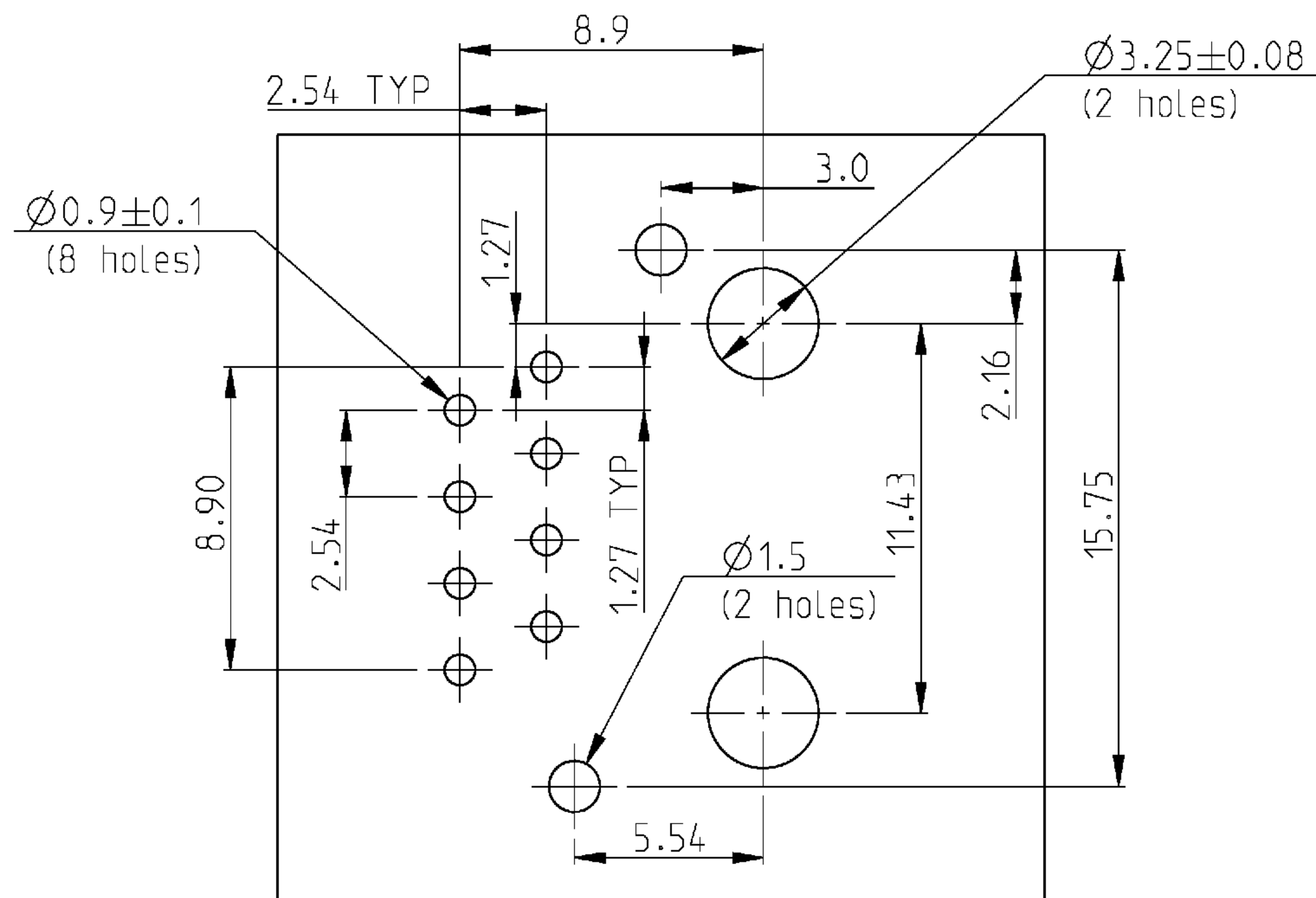
12.0 MIN. IF PLUG HAS SAME WIDTH OVER FULL LENGTH

3.7 MIN.

DEPENDENT ON APPLIED MODULAR PLUG

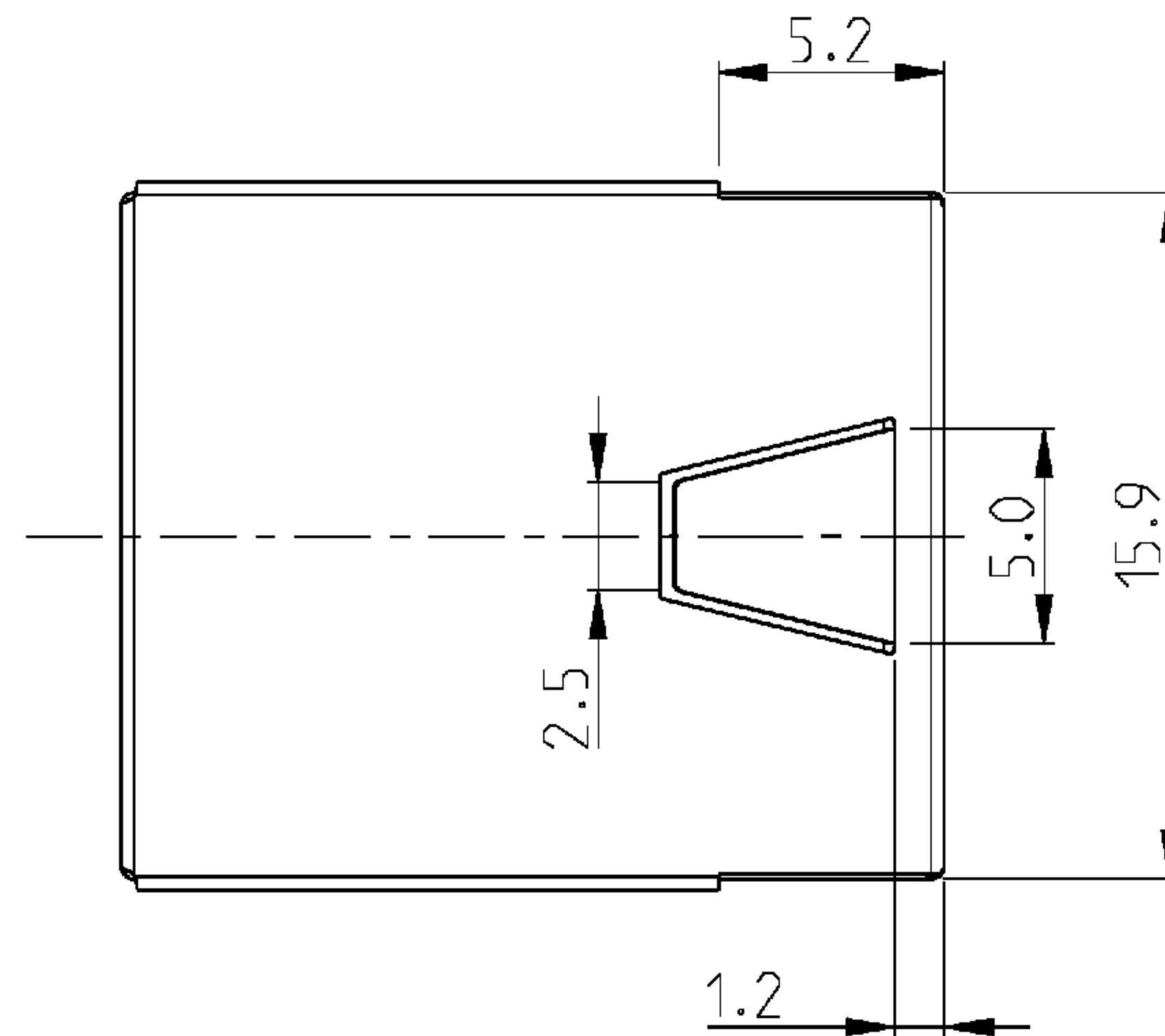


1 FOR APPLICATION INFORMATION SEE SPEC. 114-19019  
 2 FOR PERFORMANCE REQUIREMENTS SEE SPEC. 108-19064 EXCEPT SHIELDING REQUIREMENTS.



PRINTED CIRCUIT BOARD LAYOUT.

(VIEW SHOWN IS CIRCUIT (NONCOMPONENT) SIDE OF BOARD)  
 PRINTED CIRCUIT BOARD THICKNESS: 1.6 mm NOMINAL.  
 TOLERANCES UNLESS OTHERWISE SPECIFIED: ±0.05



190 PCS IN A TRAY	OVERALL: Ni 1.27µm MIN. ALL OVER THE CONTACTS SOLDER ZONE: Sn 2.5µm MIN. ON THE SOLDER ZONE OF THE CONTACT MATING ZONE: PLATING CONFIRMS TO PRODUCT REQUIREMENTS AS PER SPECIFICATION 108-19064	HOUSING: PBT UL 94V-0 BLACK CONTACTS: PHBRONZE 106066-2 SHIELD: BRASS PRE-PLATED (BRIGHT TIN)	P/N
PACKAGING	FINISH	MATERIAL	P/N

THIS DRAWING IS A CONTROLLED DOCUMENT FOR TFCO ELECTRONICS CORPORATION IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.		DWN 29 JAN 02 Verougstraete	TE Connectivity	
DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	APVD	NAME MODULAR JACK 8 POS., LOW PROFILE FULLY SHIELDED, SIDE ENTRY, WITH INSULATING TAPE	
0 PLC	±0.15	PRODUCT SPEC	SIZE A2	CAGE CODE 00779
1 PLC	±0.15	APPLICATION SPEC	DRAWING NO C=106066	RESTRICTED TO
2 PLC	±0.15		WEIGHT	
3 PLC	±0.15		CUSTOMER DRAWING	SCALE 4:1
4 PLC	±0.30			SHEET 1 OF 1
ANGLES	±0.30°			REV N
MATERIAL	FINISH			